



BZT585B5V1TQ

SURFACE MOUNT PRECISION ZENER DIODE

Features

- ±2.0% Tolerance on Breakdown Voltage
- Small, Low Profile Surface Mount Package
- Flat Lead Package Design for Low Profile and High Power Dissipation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOD523
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe.
 Solderable per MIL-STD-202, Method 208 <a>©3
- Weight: 0.001 grams (Approximate)



Top View

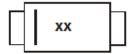
Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging	
BZT585B5V1TQ-7	Automotive	SOD523	3,000/Tape & Reel	

Notes:

- $1.\ No\ purposely\ added\ lead.\ Fully\ EU\ Directive\ 2002/95/EC\ (RoHS)\ \&\ 2011/65/EU\ (RoHS\ 2)\ compliant.$
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/quality/product_compliance_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



xx = Product Type Marking Code (See Electrical Characteristics Table)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characte	ristic	Symbol	Value	Unit
Forward Voltage	@ $I_F = 10mA$ @ $I_F = 100mA$	V _F	0.9 1.1	V
Continuous Forward Current		l _F	200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Power Dissipation (Note 6)	P_{D}	350	mW	
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{ heta JA}$	357	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C	

Note:

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Type	Marking	Zener Voltage Range (Note 7)		Maximum Zener Impedance (Note 8)		Temperature Coefficient	Total Capacitance	Maximum Reverse Current (Note 7)				
Number	Codes	V _Z @ I _{ZT}		I _{ZT}	Z _{ZT} @	Z _{ZK} @	I _{ZK}	TC @ I _{ZT}	$C_T @ f = 1MHz,$ $V_R = 0V$	I _R	@ V _R	
		Nom (V)	Min (V)	Max (V)	mA	2	Ω	mA	Typical (mV/°C)	Max (pF)	μΑ	٧
BZT585B5V1TQ	3N	5.1	5.00	5.20	5	60	480	1	-0.5	300	2	2

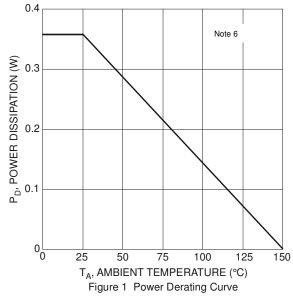
Notes:

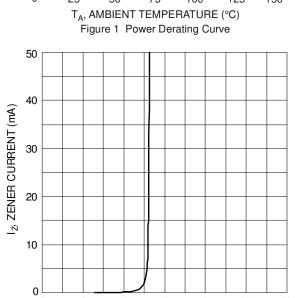
^{6.} Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com.

^{7.} Short duration pulse test used to minimize self-heating effect.

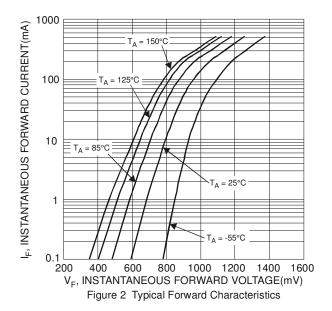
^{8.} f = 1kHz.







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Package Outline Dimensions

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Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

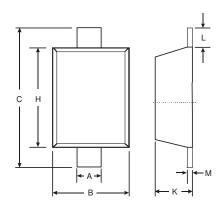
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V_z, ZENER VOLTAGE (V)
Figure 3 Typical Zener Breakdown Characteristics

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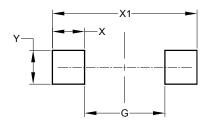


SOD523						
Dim Min Max						
Α	0.25	0.35				
В	B 0.70 0.90					
C 1.50 1.70						
H 1.10 1.30						
K 0.55 0.65						
L 0.10 0.30						
М	0.10	0.12				
All Dimensions in mm						



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.80
Х	0.60
X1	2.00
Υ	0.70

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